



# **AND190AYP**

# InGaAIP Yellow Light Emission T-3 Package (10 mm)

#### **Features**

- New emission material (InGaAIP) yellow LED
- Peak wavelength (λp = 590 nm) high bright emission
- All plastic mold type, clear colorless lens
- Low drive current, (forward current = 1 to 20 mA)
- Excellent On-Off contrast ratio
- Fast response time, capable of pulse operation
- High power luminous intensity
- Suitable for Outdoor Message Signboards

#### Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	125	mW
Operating Temperature Range	T <sub>Opr</sub>	-40 to 85	°C
Storage Temperature Range	T <sub>Sig</sub>	-40 to 120	°C

### **Electro-Optical Characteristics (T = 25°C)**

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit	
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	_	2.1	2.4	V	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	-	-	50	μΑ	
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	3,200	6,000	-	mcd	
Peak Emission Wavelength	I <sub>P</sub>	I <sub>F</sub> = 20 mA	_	590	-	nm	
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	_	13	-	nm	
Dominant Wavelength	λd	I <sub>F</sub> = 20 mA	-	587	-	nm	
Full Viewing Angle	θ	I <sub>V</sub> = 1/2 Peak	_	4	-	degree	

#### Precaution

Please be careful of the following:

- Soldering temperature: 260°C max Soldering time: 3 sec. max
  - Soldering portion of lead: up to 2 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.



## InGaAIP Yellow Light Emission











